



/ Revised record

G	2018-8				
H	2020-5-26	1			
A	2021-12-23	all	BR Q AEC-Q101 , H Q 245±5°C 5 ±0.5sec 255± 5°C 5±0.5sec		

**/ Descriptions**

SOT-23

NPN

Silicon NPN transistor in a SOT-23 Plastic Package.

/ Features

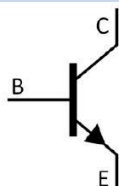
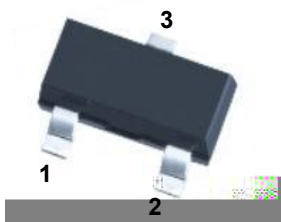
600mA

AEC-Q101

Collector currents up to 600 mA, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

/ Applications

General purpose amplifier, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit**/ Pinning**

PIN 1 Base

PIN 2 Emitter

PIN 3 Collector

/ h_{FE} Classifications & Marking

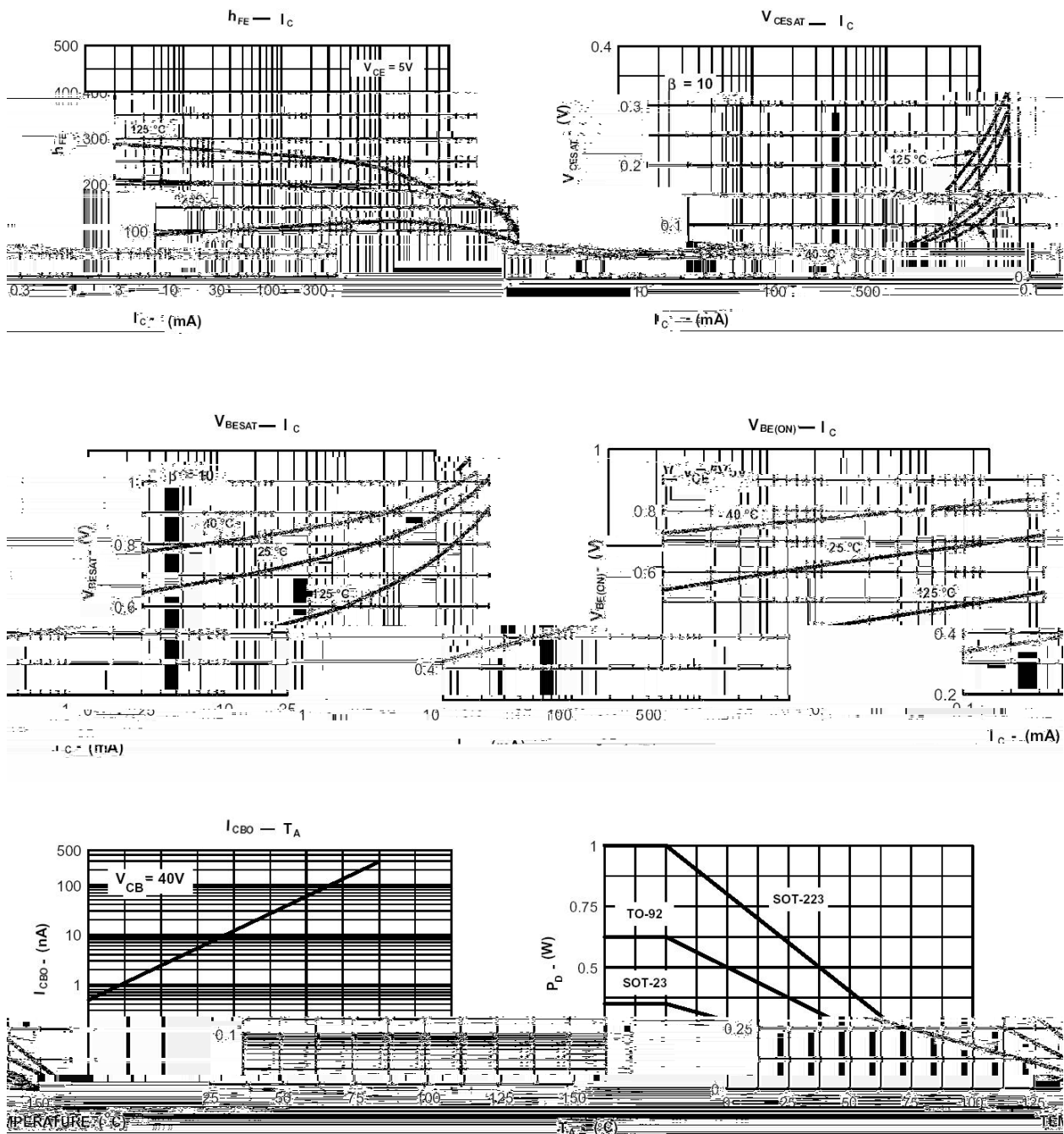
h_{FE} Range	100~300
Marking	Q1P

BRMMBT2222AQ

Rev.A Dec.-2021

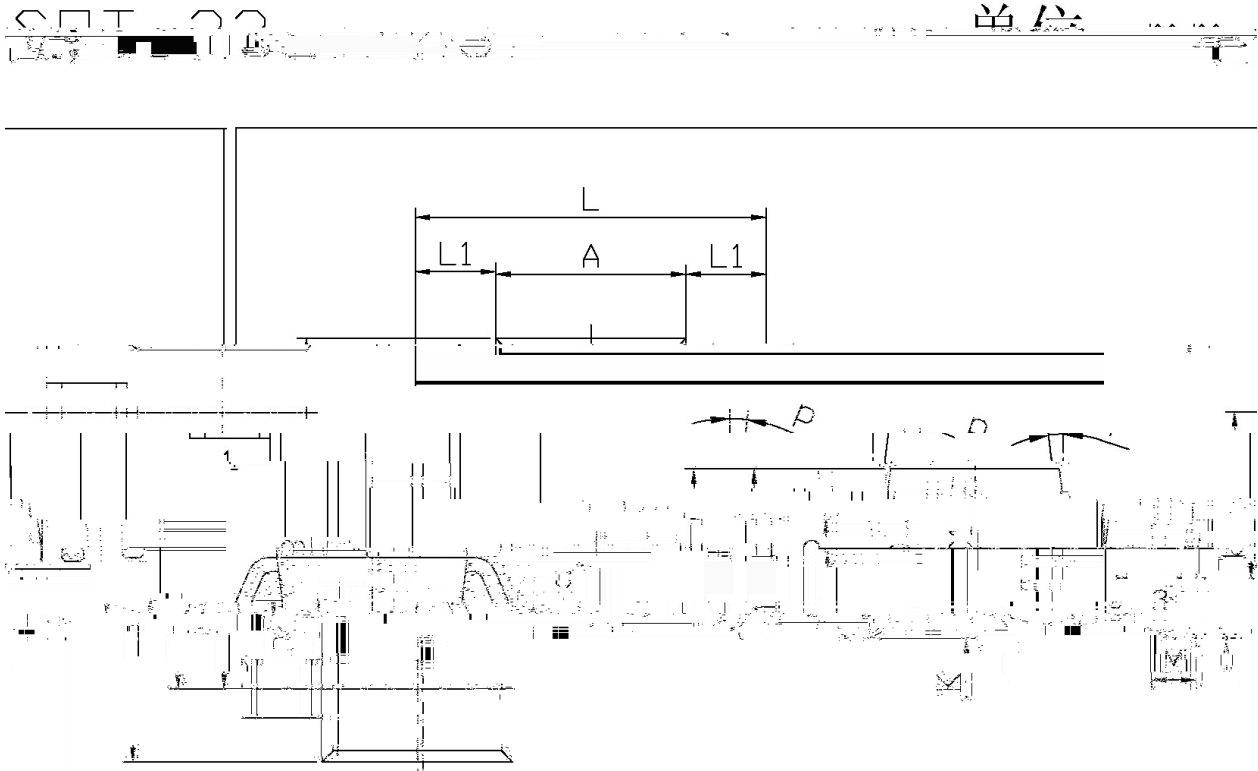
DATA SHEET

/ Electrical Characteristic Curve



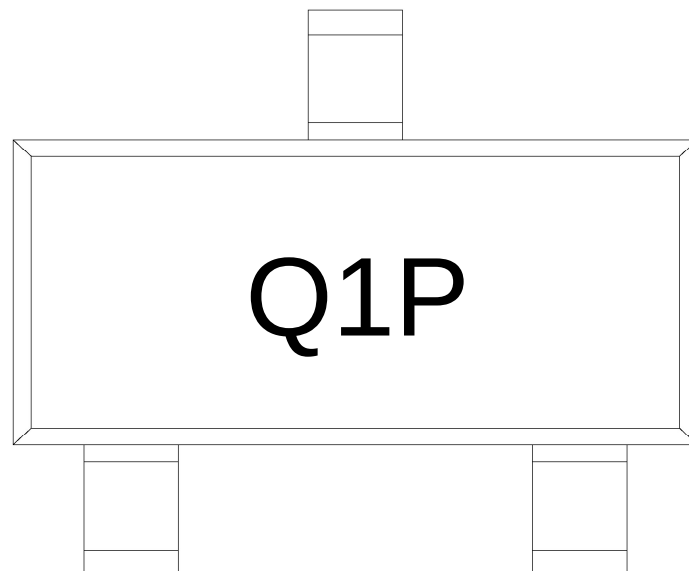


/ Package Dimensions



Dimensions in millimeters			Dimensions in millimeters		
Symbol	Min	Max	Symbol	Min	Max
L	0.90	1.20	L1	0.45	0.65
C	0.05	0.20	A	1.15	1.50
K	0	0.10	B	2.70	3.10
M	0.20MIN		E	1.70	2.10
P	7°		E1	0.85	1.05
			b	0.35	0.55

/ Marking Instructions



Q

1P

Note:

Q: Automobile halogen-free product Code

1P Product Type Code



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

说明：

- 1、预热温度 150 ~ 200℃，时间 60 ~ 120sec;
- 2、峰值温度 255±5℃，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10℃/sec.

Note:

- 1.Preheating:150~200℃, Time:60~120sec.
- 2.Peak Temp.:255±5℃, Duration:5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃

时间：10±1 sec.

Temp.:260±5℃

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱